

# NSD914XV2

## High-Speed Switching Diode

### Features

- High-Speed Switching Applications
- Lead Finish: 100% Matte Sn (Tin)
- Qualified Maximum Reflow Temperature: 260°C
- Extremely Small SOD-523 Package
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

### MAXIMUM RATINGS (T<sub>A</sub> = 25°C)

Rating	Symbol	Max	Unit
Reverse Voltage	V <sub>R</sub>	100	V
Forward Current	I <sub>F</sub>	200	mAdc
Peak Forward Surge Current	I <sub>FM(surge)</sub>	500	mAdc

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	200 1.57	mW mW/°C
Thermal Resistance Junction-to-Ambient	R <sub>θJA</sub>	635	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to 150	°C

1. FR-4 @ Minimum Pad.

Characteristic	Symbol	Min	Max	Unit
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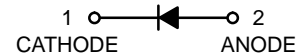
### OFF CHARACTERISTICS

Reverse Breakdown Voltage (I <sub>BR</sub> = 100 μAdc)	V <sub>(BR)</sub>	100	-	Vdc
Reverse Voltage Leakage Current (V <sub>R</sub> = 20 Vdc) (V <sub>R</sub> = 75 Vdc)	I <sub>R</sub>	-	25 5.0	nAdc μAdc
Diode Capacitance (V <sub>R</sub> = 0 V, f = 1.0 MHz)	C <sub>D</sub>	-	4.0	pF
Forward Voltage (I <sub>F</sub> = 10 mAdc)	V <sub>F</sub>	-	1.0	Vdc
Reverse Recovery Time (I <sub>F</sub> = I <sub>R</sub> = 10 mAdc)	t <sub>rr</sub>	-	4.0	ns

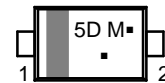


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### MARKING DIAGRAM



5D = Specific Device Code  
M = Date Code  
▪ = Pb-Free Package

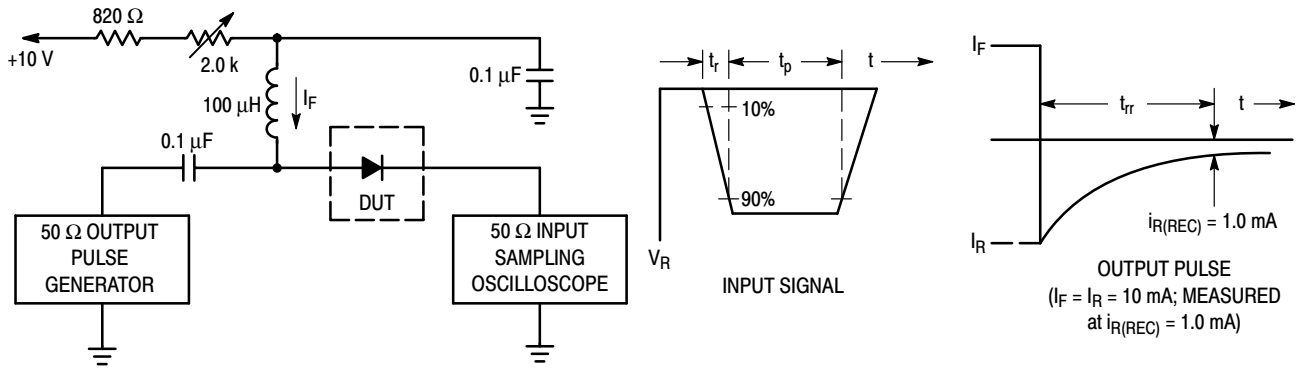
(Note: Microdot may be in either location)

### ORDERING INFORMATION

Device	Package	Shipping†
NSD914XV2T1G	SOD-523 (Pb-Free)	3000 / Tape & Reel
NSD914XV2T5G	SOD-523 (Pb-Free)	8000 / Tape & Reel

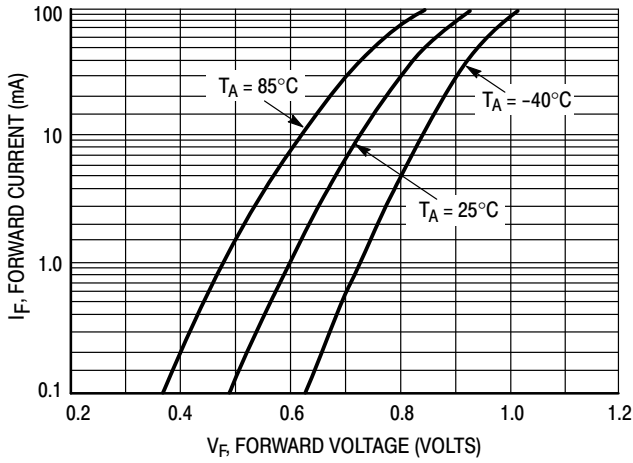
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# NSD914XV2

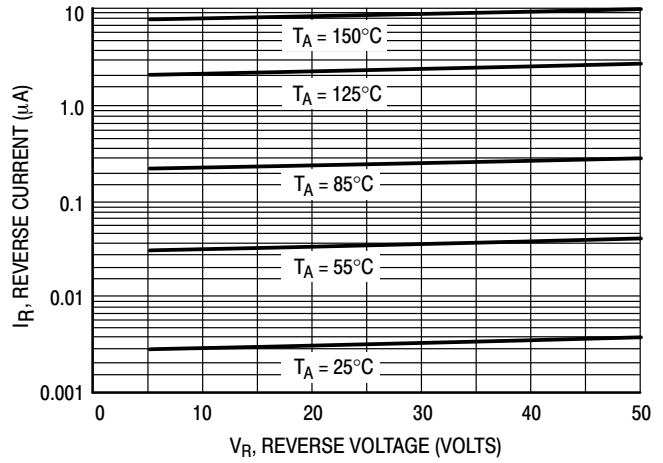


- Notes: 1. A 2.0 kΩ variable resistor adjusted for a Forward Current ( $I_F$ ) of 10 mA.  
 2. Input pulse is adjusted so  $I_{R(\text{peak})}$  is equal to 10 mA.  
 3.  $t_p \gg t_{rr}$

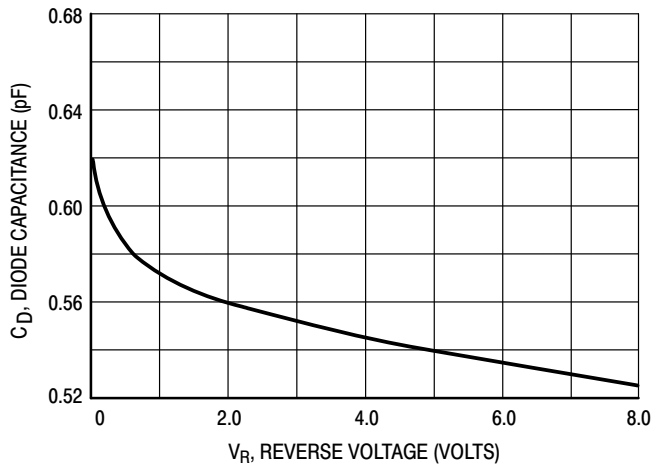
**Figure 1. Recovery Time Equivalent Test Circuit**



**Figure 2. Forward Voltage**



**Figure 3. Leakage Current**



**Figure 4. Capacitance**

# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

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**SOD-523**  
CASE 502-01  
ISSUE E

DATE 28 SEP 2010

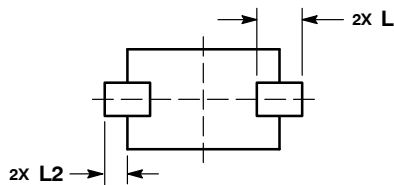
SCALE 4:1



TOP VIEW



SIDE VIEW



BOTTOM VIEW

### RECOMMENDED SOLDERING FOOTPRINT\*



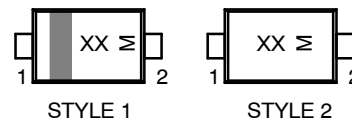
DIMENSION: MILLIMETERS

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.50	0.60	0.70
b	0.25	0.30	0.35
c	0.07	0.14	0.20
D	1.10	1.20	1.30
E	0.70	0.80	0.90
HE	1.50	1.60	1.70
L	0.30 REF		
L2	0.15	0.20	0.25

### GENERIC MARKING DIAGRAM\*



XX = Specific Device Code  
M = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

STYLE 1: PIN 1. CATHODE (POLARITY BAND)  
2. ANODE

STYLE 2: NO POLARITY

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>SOD-523</b>	<b>PAGE 1 OF 1</b>

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